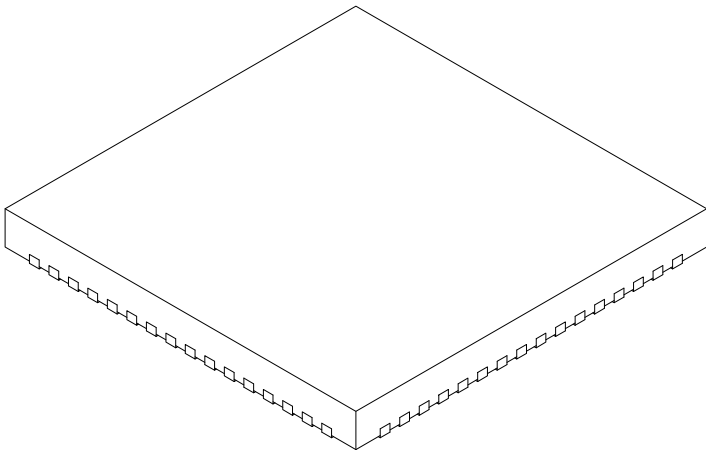


64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Units                  |    | MILLIMETERS |      |      |
|------------------------|----|-------------|------|------|
| Dimension Limits       |    | MIN         | NOM  | MAX  |
| Number of Pins         | N  | 64          |      |      |
| Pitch                  | e  | 0.50 BSC    |      |      |
| Overall Height         | A  | 0.80        | 0.90 | 1.00 |
| Standoff               | A1 | 0.00        | 0.02 | 0.05 |
| Contact Thickness      | A3 | 0.20 REF    |      |      |
| Overall Width          | E  | 9.00 BSC    |      |      |
| Exposed Pad Width      | E2 | 5.30        | 5.40 | 5.50 |
| Overall Length         | D  | 9.00 BSC    |      |      |
| Exposed Pad Length     | D2 | 5.30        | 5.40 | 5.50 |
| Contact Width          | b  | 0.20        | 0.25 | 0.30 |
| Contact Length         | L  | 0.30        | 0.40 | 0.50 |
| Contact-to-Exposed Pad | K  | 0.20        | -    | -    |

**Notes:**

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated.
- 3. Dimensioning and tolerancing per ASME Y14.5M.
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.